

Substitute form 1449A/PTO

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

(use as many sheets as necessary)

Sheet 1 of 5 A4

Complete if Known

Application Number 10/601,938
 Filing Date June 23, 2003
 First Named Inventor Krishna K. Nair
 Group Art Unit 2829
 Examiner Name Douglas M. Menz
 Attorney Docket Number 9180-29

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		Number	Kind Code (if known)		
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Examiner Signature

Doug Menz

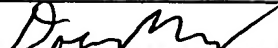
Date Considered

6/7/05

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Substitute form 1449A/PTO				Complete if Known	
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INFORMATION DISCLOSURE STATEMENT BY APPLICANT (use as many sheets as necessary)				Filing Date	June 23, 2003
				First Named Inventor	Krishna K. Nair
				Group Art Unit	2829
				Examiner Name	Douglas M. Menz
Sheet	2	of 5	A4	Attorney Docket Number	9180-29

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Examiner Signature		Date Considered	6/7/05
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			First Named Inventor	Krishna K. Nair	
			Group Art Unit	2829	
			Examiner Name	Douglas M. Menz	
Sheet	3	of 5	A4	Attorney Docket Number	9180-29

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Sheet	4	of 5	A4	Attorney Docket Number	9180-29

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Sheet	5	of 5	A4	Attorney Docket Number	9180-29

<i>OP</i>	Electronics Packaging Conference, Austin, Texas, pp 14-25 (Sep. 29-Oct. 1, 1996).
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